

#### DDR4 DIMM

TE Internal #: 2309409-1 SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 260 Position, DDR4 DIMM View on TE.com >



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: Small Outline (SO) Stack Height: 5.2 mm [.205 in ] Module Orientation: Right Angle Connector System: Cable-to-Board Number of Positions: 260

All DDR4 SO DIMM Sockets (39)

### Features

#### Product Type Features

DRAM Type

 $\cap$ ctor Suct Small Outline (SO)

Coble to Boord

Connector System	Cable-to-Board	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Number of Keys	1	
Number of Rows	2	
Module Orientation	Right Angle	
Number of Positions	260	
Electrical Characteristics		
DRAM Voltage	1.2 V	
Signal Characteristics		
SGRAM Voltage	1.2 V	
Body Features		
Ejector Location	Both Ends	
Latch Material	High Temperature Thermoplastic	
Retention Post Location	Both Ends	

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Module Key Type	Offset Left
Ejector Type	Locking
Connector Profile	Low
Contact Features	
Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max)	.5 A
Termination Features	
Insertion Style	Cam-In
Mechanical Attachment	
Mating Alignment Type	Standard Keying
PCB Mounting Style	Surface Mount
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount

### Housing Features

Housing Material	High Temperature Thermoplastic	
Housing Color	Black	
Centerline (Pitch)	.5 mm, 3.3 mm[.02 in][.129 in]	
Dimensions		
Stack Height	5.2 mm[.205 in]	
Row-to-Row Spacing	8.2 mm[.322 in]	
Usage Conditions		
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]	
Operating Temperature Range Operation/Application	-55 – 85 °C[-67 – 185 °F]	
	-55 – 85 °C[-67 – 185 °F] Power	
Operation/Application		
Operation/Application Circuit Application		
Operation/Application Circuit Application Industry Standards	Power	

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Packaging Quantity	800
Packaging Method	Tape & Reel
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**



## Also in the Series DDR4 DIMM

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# **Customers Also Bought**



TE Part #2176331-9 CRGP 2512 47R 1%	TE Part #2174918-1 PUSH-PUSH SIM CONNECTOR SUPER LOWPROFILE	TE Part #2-1419108-0 RT444024F
	TE TE	
TE Part #244838-E SMCQ 50 M AB VV 8-13 CL * H007 137	TE Part #3-2176421-2 TLRP 2512 2.0W R075 1% 25PPM 4K RL	

### Documents

Product Drawings DDR4 SODIMM 260P 5.2H STD

English

E005

**CAD** Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_2309409-1\_1.2d\_dxf.zip

SMCQ 26 M AB VV 8-13 CL \* H007 137

E005

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English Customer View Model ENG\_CVM\_CVM\_2309409-1\_1.3d\_igs.zip English Customer View Model

ENG\_CVM\_CVM\_2309409-1\_1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English